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Spec No.	DG-099004B
Issue	30-Oct-09

SPECIFICATIONS

Product Type

Light Emitting Diode Module

Model No.

GW5BTC27K00

%These specifications contain14 pages including the cover and appendix. If you have any objections, please contact us before issuing purchasing order.

CUSTOMERS ACCEPTANCE

DATE:

BY:

PRESENTED BY: M.Katoh

Dept. General Manager

REVIEWED BY:

PREPARED BY:

Development Department II System Device DivisionIII Electronic Components And Devices Group SHARP CORPORATION

REFERENCE

• Handle this document carefully for it contains material protected by international copyright law. Any reproduction, full or in part, of this material is prohibited without the express written permission of the company.

• When using the products covered herein, please observe the conditions written herein and the precautions outlined in the following paragraphs. In no event shall the company be liable for any damages resulting form failure to strictly adhere to these conditions and precautions.

(1) The products covered herein are designed and manufactured for the following application areas. When using the products covered herein for the equipment listed in paragraph (2), even for the following application areas, be sure to observe the precautions given in Paragraph (2). Never use the products for the equipment listed in Paragraph (3).

- \cdot Office electronics
- ·Instrumentation and measuring equipment
- Machine tools
- ·Audiovisual equipment
- \cdot Home appliances
- ·Communication equipment other than for trunk lines

(2) These contemplating using the products covered herein for the following equipment which demands high reliability, should first contact a sales representative of the company and then accept responsibility for incorporating into the design fail-safe operation, redundancy, and other appropriate measures for ensuring reliability and safety of the equipment and the overall system.

• Control and safety devices for airplanes, trains, automobiles, and other transportation equipment

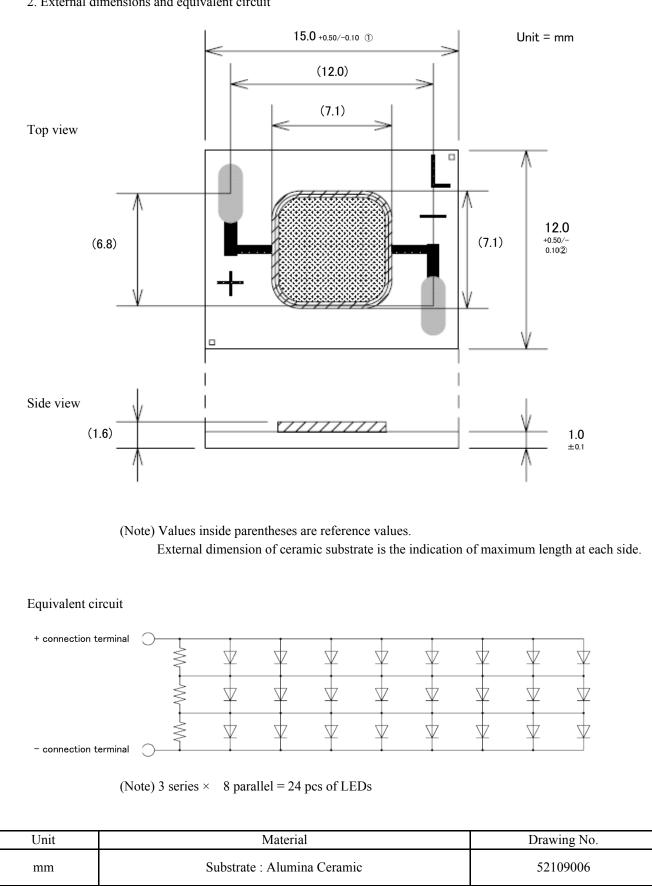
- Mainframe computers
- traffic control systems
- ·Gas leak detectors and automatic cutoff devices
- ·Rescue and security equipment
- ·Other safety devices and safety equipment, etc.
- (3) Do not use the products covered herein for the following equipment which demands extremely high performance in terms of functionality, reliability, or accuracy
 - · Aerospace equipment
 - •Communications equipment for trunk lines
 - ·Control equipment for the nuclear power industry
 - ·Medical equipment related to life support, etc.
- (4) please direct all queries and comments regarding the interpretation of the above three Paragraphs to a sales representative of the company.

 Please direct all queries regarding the products covered herein to a sales representative of the company.

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GW5BTC27K00 sp	ecifications
 Application These specifications apply to the light emitting diode model. [High color rendering Bulb Color (from InGaN Blue LEMA Main application : Lighting 	
2. External dimensions and equivalent circuit	Refer to Page 2.
3. Ratings and characteristics	Refer to Page 3 - 5.
3-1. Absolute maximum ratings	
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6-4. Indication printed on product	
7. Precautions	Refer to Page 10 - 12.

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2. External dimensions and equivalent circuit



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3. Ratings and characteristics

3-1. Absolute maximum ratings

Item	Symbol	Rating	Unit
Power Dissipation *1,4	Р	4.6	W
Forward Current *1,4	I _F	400	mA
Reverse Voltage *2,4	V _R	-15	V
Operating Temperature *3	T _{opr}	- 30 ~ + 90	°C
Storage Temperature	T _{stg}	$-40 \sim +100$	°C

*1 Power dissipation and forward current are the value when the module temperature is set lower than the rating by using an adequate heat sink.

*2 Voltage resistible at initial connection error

(Not dealing with the possibility of always-on reverse voltage.)

*3 Case temperature Tc (Refer to measuring point for case temperature in the next page.) Refer to "Derating curve" in the next page as for operating current.

*4 $T_c = 25 \ ^{\circ}C$

3-2. Electro-optical characteristics

 $(T_c = 25 \ ^{\circ}C)$

						()
Item	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Forward Voltage *5	$V_{\rm F}$	$I_{\rm F} = 360 {\rm mA}$	9.0	(10.2)	11.5	V
Luminous Flux *6	Φ	$I_{\rm F} = 360 {\rm mA}$	150	(200)	-	lm
Chromaticity Coordinates *7	х	$I_{\rm F} = 360 {\rm mA}$	-	(0.464)	-	-
Chromatienty Coordinates • 7	У	$I_{\rm F} = 500 {\rm mA}$	-	(0.418)	-	-
Color Temperature	-	$I_{\rm F} = 360 {\rm mA}$	(2600)	(2700)	(2800)	K
Color Rendering Index *8	Ra	$I_{\rm F} = 360 {\rm mA}$	83	(87)	-	-

(Note) Values inside parentheses are shown for reference purpose only.

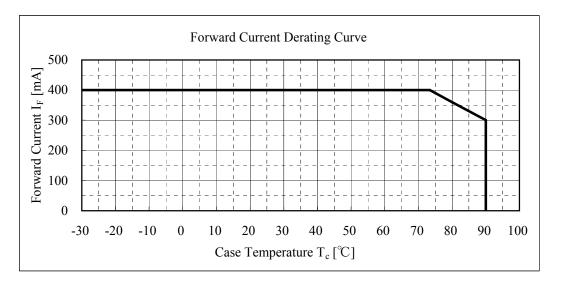
- *5 After 20 ms drive, Measuring allowance: \pm 3 %
- *6 Monitored by Sharp's 8 inch integrating sphere and Otsuka electronics MCPD-LE3400 (After 20 ms drive, Measuring error: ± 20 %)
- *7 Monitored by Sharp's 8 inch integrating sphere and Otsuka electronics MCPD-LE3400 (After 20 ms drive, Measuring error: ± 0.01)
- *8 Monitored by Sharp's 8 inch integrating sphere and Otsuka electronics MCPD-LE3400 (After 20 ms drive, Measuring error: ±4)

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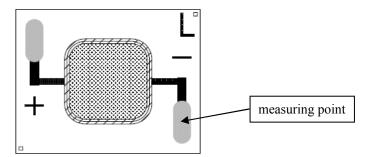
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3-3. Derating curve



(Note) To keep the case temperature lower than the rating, enough heat-radiation performance needs to be secured by using an adequate heat sink.

(Measuring point for case temperature)

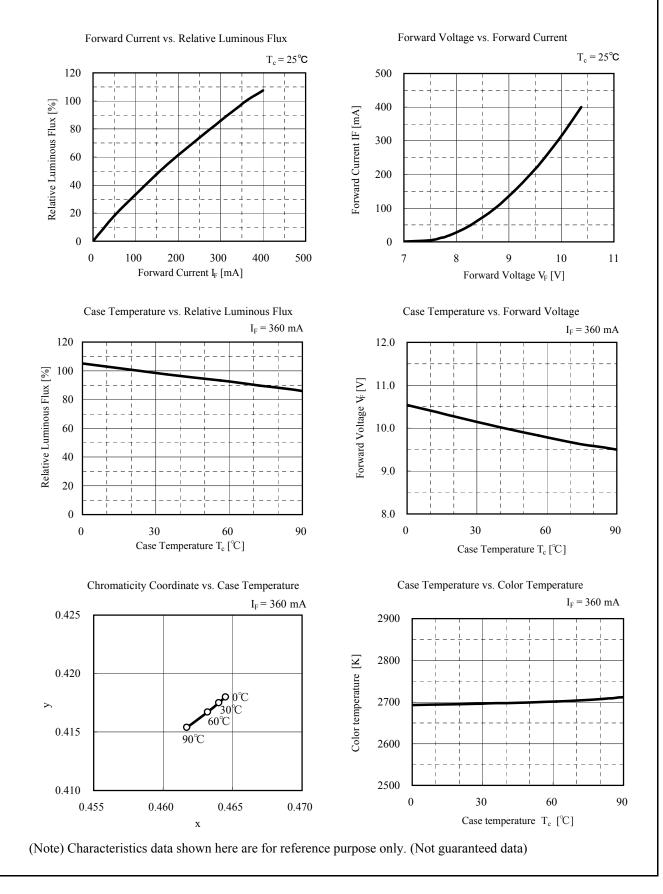


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3-4. Characteristics diagram (TYP.)



4. Reliability

The reliability of products shall be satisfied with items listed below.

4-1.7	Test items and test condit	Co	nfidence le	vel: 90 %	
No.	Test item	Test conditions	Samples	Defective	LTPD
			n	С	(%)
1	Temperature Cycle	- 40 °C(30 min) \sim + 100 °C(30 min), 100 cycles			
			11	0	20
2	Temperature Humidity	$T_{stg} = +60 ^{\circ}\text{C}, \text{RH} = 90 ^{\circ}\text{, Time} = 1000 \text{ h}$			
	Storage		11	0	20
3	High Temperature	$T_{stg} = +100^{\circ}C$, Time = 1000 h			
	Storage		11	0	20
4	Low Temperature	$T_{stg} = -40 \text{ °C}, \text{ Time} = 1000 \text{ h}$			
	Storage		11	0	20
5	Steady State Operating	$T_c = 60 \text{ °C}, I_F = 400 \text{ mA}, \text{ Time} = 1000 \text{ h}$			
	Life		11	0	20
6	Shock	Acceleration: 15000 m/s ² , Pulse width: 0.5 ms			
		Direction: 3 directions (X, Y and Z)			
		3 trials in each direction	5	0	50
7	Vibration	Frequency: 100 to 2000 Hz for 4 minutes per trial			
		Acceleration: 200 m/s ²			
		Direction: 3 directions (X, Y and Z)			
		4 trials in each direction	5	0	50

4-2. Failure criteria

No.	Parameter	Symbol	Failure criteria
1	Forward Voltage	$V_{\rm F}$	$V_F > U.S.L \times 1.1$
2	Luminous Flux	Φ	$\Phi \le$ Initial value $\times 0.7$

(Note) U.S.L. stands for Upper Specification Limit.

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- 5. Quality level
- 5-1. Applied standard ISO2859-1
- 5-2. Sampling inspection

A single normal sampling plan, level S-4.

5-3. Inspection items and defect criteria

No.	Item	Defect criteria	Classification	AQL
1	No radiation	No light emitting	Major	
			defect	0.1%
2	Electro-optical	Not conforming to the specification		
	characteristics	(Forward voltage, Luminous flux and Chromaticity)		
3	External	Not conforming to the specified dimensions		
	dimensions	(External dimensions of $①$ and $②$ shown in Page 2)		
4	Appearance	Nonconformity observed in product appearance is determined	Minor	
		as defective only when electro-optical characteristics is affected by.	defect	0.4%
		<if above="" any="" arises="" criterion="" mentioned="" of="" question="" regardless=""></if>		
		Foreign material, scratch, or bubble at emitting area: 0.8 mm φ		
		■ Fiber generation at emitting area: 0.2 mm in width and 2.5 mm in length		
		Foreign material at connection terminal: 0.8 mm φ		
		■ Substrate burr on edge: Over dimension tolerance		

(Note) Products with removable foreign material attached on is not determined to be defective.

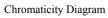
- 6. Supplements
- 6-1. Chromaticity rank table

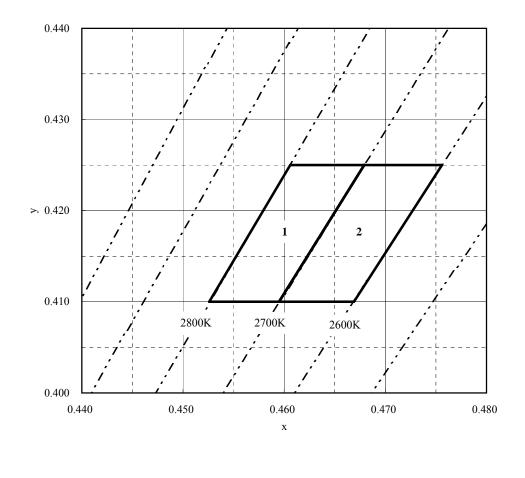
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	$(I_F =$	360	mA,	$T_c =$	25	°C)
4: .: 4		d:	haa			

	Chromaticity coordinates				
	Point 1	Point 2	Point 3	Point 4	
Х	0.4606	0.4526	0.4669	0.4756	
у	0.4250	0.4100	0.4100	0.4250	

Rank		Chromaticity coordinates			
Nalik		Point 1	Point 2	Point 3	Point 4
1	х	0.4606	0.4526	0.4595	0.4679
ı y	0.4250	0.4100	0.4100	0.4250	
2	х	0.4679	0.4595	0.4669	0.4756
2	у	0.4250	0.4100	0.4100	0.4250



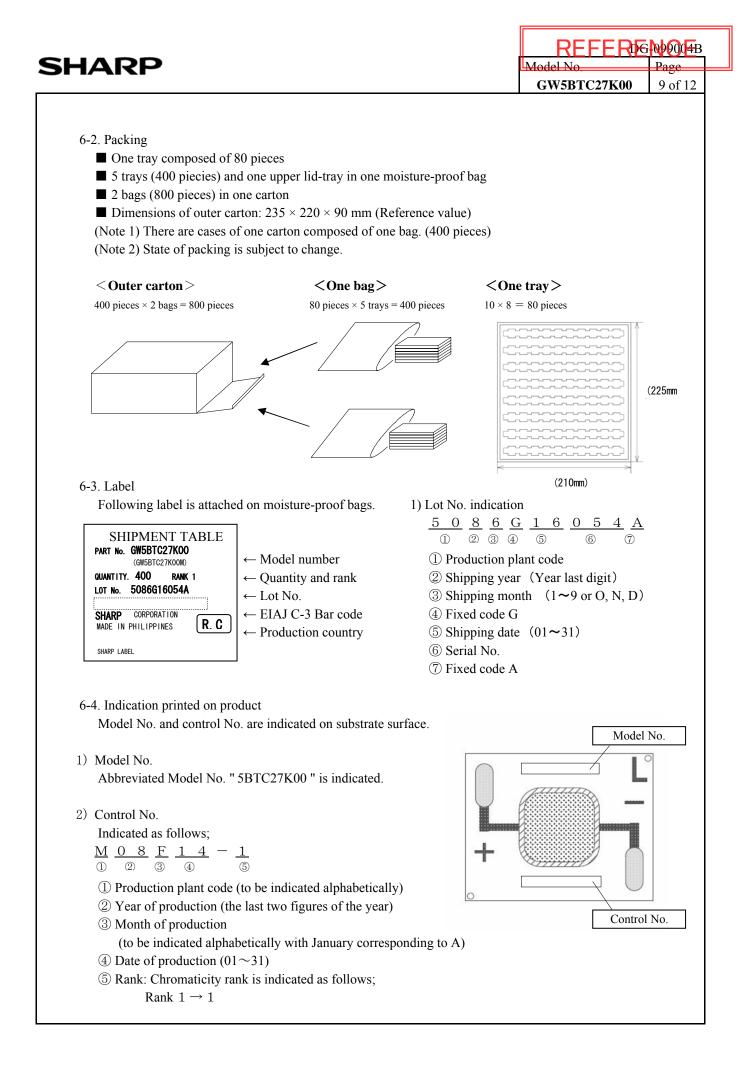


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(Tolerance: $x,y \pm 0.01$)



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7. Precautions

① Storage conditions

Please follow the conditions below.

• Before opened: Temperature 5 \sim 30 °C, Relative humidity less than 60 %.

(Before opened LED should be used within a year)

 \cdot After opened: Temperature 5 \sim 30 °C, Relative humidity less than 60 %.

(Please apply soldering within 1 week)

•After opened LED should be kept in an aluminum moisture proof bag with a moisture absorbent material (silica gel).

• Avoid exposing to air with corrosive gas.

If exposed, electrode surface would be damaged, which may affect soldering.

② Usage conditions

The products are not designed for the use under any of the following conditions.

- Please confirm their performance and reliability well enough if you use under any of the following conditions;
- In a place with a lot of moisture, dew condensation, briny air, and corrosive gas.

(Cl, H2S, NH3, SO2, NOX, etc.)

- Under the direct sunlight, outdoor exposure, and in a dusty place.
- In water, oil, medical fluid, and organic solvent.

3 Heat radiation

If the forward current (I_F) is applied to single-state module at any current, there is a risk of damaging module or emitting smoke.

Equip with specified heat radiator, and avoid heat stuffed inside the module.

④ Installation

Material of board is alumina ceramic. If installed inappropriately, trouble of no radiation may occur due to board crack or overheat. Please take particular notice for installing method. Further information on installation, refer to the following cautions.

- Apply thermolysis adhesive, adhesive sheet or peculiar connector when mounted on heat radiator. In case of applying adhesive or adhesive sheet only, check the effectiveness and reliability before fixing. If LED comes off from the heat radiator, unusual temperature rise entails hazardous phenomena including device deterioration, coming off of solder at leads, and emitting smoke.
- When LED device is mechanically fixed or locked, Please take it into consideration regarding method of attach due to fail from stress.
- Avoid convexly uneven boards. Those convex boards are subject to substrate cracking or debasement of heat release.
- It is recommended to apply adhesive or adhesive sheet with high thermal conductivity to radiate heat effectively.
- Please take care about the influence of color change of adhesive or adhesive sheet in initial and long term period, which may affect light output or color due to change of reflectance from backside.

5 Module surface strength

Module surface is subject to mechanical stress. Applying stress to surface of modules results in damage on resin and internal failure. Please do not pressurize on the part of resin.

6 Connecting method

In case of solder connecting method, follow the conditions mentioned below.

- Use Soldering iron with thermo controller (tip temperature 380 °C), within 5 seconds per one place.
- Secure the solderwettability on whole solder pad and leads.

• During the soldering process, put the ceramic board on materials whose conductivity is poor enough not to radiate heat of soldering.

- Warm up (with using a heated plate) the substrate is recommended before soldering.
- Avoid touching a part of resin with soldering iron.
- This product is not designed for reflow and flow soldering.
- · Avoid such lead arrangement as applying stress to solder-applied area.
- Please do not detach solder and make re-solder.
- Please solder evenly on each electrodes.
- Please prevent flux from touching to resin.

⑦ Static electricity

This product is subject to static electricity, so take measures to cope with it. Install circuit protection device to drive circuit, if necessary.

8 Drive method

• Any reverse voltage cannot be applied to LEDs when they are in operation or not. Design a circuit so that any flow of reverse or forward voltage can not be applied to LEDs

when they are out of operation.

• Module is composed of LEDs connected in both series and parallel.

Constant voltage power supply runs off more than specified current amount due to lowered V_F caused by temperature rise.

Constant current power supply is recommended to drive.

③ Cleaning

Avoid cleaning, since silicone resin is eroded by cleaning.

1 Color-tone variation

Chromaticity of this product is monitored by integrating sphere right after the operation. Chromaticity varies depending on measuring method, light spread condition, or ambient temperature. Please verify your actual conditions before use.

11 Safety

• Looking directly at LEDs for a long time may result in hurt your eyes.

•In case that excess current (over ratings) are supplied to the device, hazardous phenomena including abnormal heat generation, emitting smoke, or catching fire can be caused.

Take appropriate measures to excess current and voltage.

• In case of solder connecting method, there is a possibility of fatigue failure by heat.

Please fix the leads in such case to protect from short circuit or leakage of electricity caused by contact.

- Please confirm the safety standards or regulations of application devices.
- Please careful not to injure your hand by edge of ceramic substrate.

1 Other cautions

Guarantee covers the compliance to the quality standards mentioned in the Specifications, however it does not cover the compatibility with application of the end-use, including assembly and usage environment.

In case any quality problems occurred in the application of end-use, details will be separately discussed and determined between the parties hereto.